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Flexible Electronic Materials and Devices: Preparation and Application

Guest Editor:

Dr. Shu-Jen Wang
Department of Physics, Hong Kong Baptist University, Kowloon Tong, Hong Kong, China

Deadline for manuscript submissions:
closed (20 November 2025)

Message from the Guest Editor

Dear Colleagues,

Flexible electronics have advanced significantly in the past decade, enabling their application in numerous domains where conventional rigid electronics cannot be applied, such as bioelectronics and electronic sensors, etc. Two main strategies have been proposed to introduce flexibility in electronic materials: reducing the thickness of commercially available inorganic semiconductor materials and designing novel semiconductor materials with intrinsic mechanical flexibility. Further advances in flexible electronic devices would require the matrimony of material synthesis, device physics and engineering, and advanced characterization expertise to enable the development of high-performance devices with decent reliability for practical real-world applications.

This Special Issue aims to compile research papers, short communications, and review articles focused on the synthesis of novel materials, device design, fabrication, and the advanced characterization of various flexible electronic devices for the identication of the main milestones in the roadmap of future flexible electronics research.

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Editor-in-Chief

Prof. Dr. Maryam Tabrizian
1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada
2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

Message from the Editor-in-Chief

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Contact Us

Materials Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
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𝕏@Materials_Mdpi